

Multilayer Ceramic Chip Capacitors for Automotive

A0402X5R105K250NTB (0402,X5R,1 μF,DC 25 V)

1. Scope

This specification applies to Automotive-grade Multilayer Ceramic Chip Capacitors (MLCCs). Specifically intended for: automotive infotainment applications and non-safety-critical automotive smart systems.

Application Scope: In-Vehicle Infotainment (IVI) systems; Smart cockpits; Intelligent Parking Assist (IPA); Electronic Toll Collection (ETC); In-vehicle wireless charging, etc.

2. Part Number System

A	0402	X5R	105	K	250	N	T	B
①	②	③	④	⑤	⑥	⑦	⑧	⑨
Series Code	Size Code	Temperature Characteristics	Nominal Capacitance	Capacitance Tolerance	Rated Voltage	Termination Type	Packaging Code	Thickness Code

① Series Code A-Multilayer Ceramic Chip Capacitors for Automotive

② Size Code (Unit: mm)

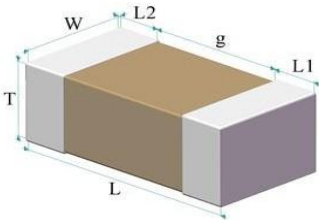


Fig.1 Structure & Dimension

Size Code	L	W	L1,L2	g	T	⑨ Thickness Code
0402	1.00 ± 0.05	0.50 ± 0.05	0.15-0.35	0.30 min	0.50 ± 0.05	B

③ Temperature Characteristics

Temperature Characteristics	Operating Temp. Range	Temperature Characteristics		
		Temp. coeff. or Cap. Change	Temp. Range	Ref. Temp.
X5R	-55 °C-85 °C	±15%	-55 °C-85 °C	25 °C

④ Nominal Capacitance

Code	Nominal Capacitance
105	1 μF

⑤ Capacitance Tolerance

Code	Capacitance Tolerance
K	±10%

⑥ Rated Voltage

Code	Voltage Values
250	DC 25 V

⑦ Termination Type

Code	Terminal Electrodes	Plating Material
N	Cu	Ni/Sn

⑧ Packaging Code

Code	Square Hole Spacing	Disc Size	Carrier Tape	QTY (Kpcs)
T	2 mm	7 "	Paper	10

3. Technical Specifications and Test Methods

1. Operating Environment

Temp. Characteristics	Temp. Range	Relative Humidity	Atmospheric Pressure
X5R	-55 °C-85 °C	≤95% (25 °C)	86 kPa-106 kPa

3.2 Reliability Test Specifications and Methods

Table 1: Specifications and Test Methods

No.	Item AEC-Q200 Test Item		Specification Class 2 (High dielectric constant type)	Test Method																
1	Pre-and Post-Stress Electrical Test																			
2	High Temperature Exposure (Storage)	Appearance Cap. Change IR (Room Temp.) DF	No defects or abnormalities. $\Delta C/C \leq \pm 12.5\%$ ≥ 500 Mfi or 25 fi•F, (Whichever is smaller) 0.2 max	Pre-treatment Subjected to 3 cycles of lead-free reflow at 260 °C (standard profile) for thermal shock testing, with ~30 minutes between cycles. Test temperature Test time Post-treatment	Perform heat treatment at (150 +0/−10) °C for 1 h, then soak at room temperature for (24 ± 2) h, then measure. 85 °C ± 3 °C (1000 ± 12) h Let sit for (24 ± 2) h at room temperature, then measure.															
3	Temperature Cycling	Appearance Cap. Change IR (Room Temp.) DF	No defects or abnormalities. $\Delta C/C \leq \pm 10\%$ ≥ 1000 Mfi or 50 fi•F, (Whichever is smaller) 0.2 max	Pre-treatment Subjected to 3 cycles of lead-free reflow at 260 °C (standard profile) for thermal shock testing, with ~30 minutes between cycles. Mounting method The number of cycles Temperature Step <table><tr><td>Step</td><td>Temp.(°C)</td><td>Time (min)</td></tr><tr><td>1</td><td>-55</td><td>30 ± 3</td></tr><tr><td>2</td><td>25</td><td>1</td></tr><tr><td>3</td><td>85</td><td>30 ± 3</td></tr><tr><td>4</td><td>25</td><td>1</td></tr></table> Post-treatment	Step	Temp.(°C)	Time (min)	1	-55	30 ± 3	2	25	1	3	85	30 ± 3	4	25	1	Perform heat treatment at (150 +0/−10) °C for 1 h, then soak at room temperature for (24 ± 2) h, then measure. Solder the capacitor to the test substrate 1000 cycles Let sit for (24 ± 2) h at room temperature, then measure.
Step	Temp.(°C)	Time (min)																		
1	-55	30 ± 3																		
2	25	1																		
3	85	30 ± 3																		
4	25	1																		
4	Destructive Physical Analysis (DPA)		No defects or abnormalities.	EIA-469																
5	Biased Humidity (8585)	Appearance Cap. Change IR (Room Temp.) DF	No defects or abnormalities. $\Delta C/C \leq \pm 12.5\%$ ≥ 100 Mfi or 5 fi•F, (Whichever is smaller) 0.2 max	Pre-treatment Subjected to 3 cycles of lead-free reflow at 260 °C (standard profile) for thermal shock testing, with ~30 minutes between cycles. Mounting method Test temperature Test humidity Test time Test voltage The charge/discharge current Post-treatment	Perform heat treatment at (150 +0/−10) °C for 1 h, then soak at room temperature for (24 ± 2) h, then measure. Solder the capacitor to the test substrate (85 ± 3) °C (85 ± 3)% RH (1000 ± 12) h Rated voltage (U _R ≤ 1000 V) and 1.3 V-1.5 Vdc (Add 100 kfi resister) 1000 ± 50 V (U _R > 1000 V) and 1.3 V-1.5 Vdc (Add 100 kfi resister) Note: For silver-containing ceramics (e.g., palladium-silver electrodes), low-voltage partial testing must be carried out simultaneously. ≤ 50 mA Perform heat treatment at (150 +0/−10) °C for 1 h, then soak at room temperature for (24 ± 2) h, then measure.															

Table 1: Specifications and Test Methods

No.	Item AEC-Q200 Test Item		Specification Class 2 (High dielectric constant type)	Test Method	
6	Operational Life	Appearance Cap. Change IR (Room Temp.) DF	No defects or abnormalities. $\Delta C/C \leq \pm 12.5\%$ $\geq 100 \text{ Mfi or } 5 \text{ fi}\cdot\text{F}$, (Whichever is smaller) 0.2 max	Pre-treatment Subjected to 3 cycles of lead-free reflow at 260 °C (standard profile) for thermal shock testing, with ~30 minutes between cycles. Mounting method Test temperature Test time Test voltage The charge/discharge current Post-treatment	Perform heat treatment at (150 +0/−10) °C for 1 h, then soak at room temperature for (24 ± 2) h, then measure. Solder the capacitor to the test substrate 85 °C ± 3 °C (1000 ± 12) h $1.0 \times U_R$ $\leq 50 \text{ mA}$ Perform heat treatment at (150 +0/−10) °C for 1 h, then soak at room temperature for (24 ± 2) h, then measure.
7	Appearance		No defects or abnormalities.	Visual inspection under 10x microscope	
8	Physical Dimension		See Fig.1	Measuring by gages which precision is not less than 0.01 mm.	
9	Mechanical Shock	Appearance Cap. Change IR (Room Temp.) DF	No defects or abnormalities. Within the specified initial value $\geq 1000 \text{ Mfi or } 50 \text{ fi}\cdot\text{F}$, (Whichever is smaller) Within the specified initial value	Subjected to 3 cycles of lead-free reflow at 260 °C (standard profile) for thermal shock testing, with ~30 minutes between cycles. Mounting method Holding Time Peak value Velocity change Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks).	Solder the capacitor to the test substrate 0.5 ms 1500 g 4.7 m/s
10	Vibration	Appearance Cap. Change IR (Room Temp.) DF	No defects or abnormalities. Within the specified initial value $\geq 1000 \text{ Mfi or } 50 \text{ fi}\cdot\text{F}$, (Whichever is smaller) Within the specified initial value	Subjected to 3 cycles of lead-free reflow at 260 °C (standard profile) for thermal shock testing, with ~30 minutes between cycles. Mounting method Frequency Amplitude Vibration Time This motion should be applied for 12 cycles in each 3 mutually perpendicular directions (total of 36 times).	Solder the capacitor to the test substrate 10 Hz to 2000 Hz and return to 10 Hz 1.5 mm 20 min
11	Resistance to Soldering Heat	Appearance Cap. Change IR (Room Temp.) DF	No defects or abnormalities. $\Delta C/C \leq \pm 15\%$ $\geq 1000 \text{ Mfi or } 50 \text{ fi}\cdot\text{F}$, (Whichever is smaller) Within the specified initial value	Pre-treatment Pre-heating Test Method Solder alloy Solder temp. Duration of immersion Depth of immersion Post-treatment	Perform heat treatment at (150 +0/−10) °C for 1 h, then soak at room temperature for (24 ± 2) h, then measure. 120 °C-150 °C, Time: 60 s Solder bath Sn-Ag-Cu (Lead Free Solder) (260 ± 5) °C (10 ± 1) s (10 ± 1) mm Let sit for (24 ± 2) h at room temperature, then measure.
12	ESD	Appearance Cap. Change IR (Room Temp.) DF	No defects or abnormalities. Within the specified initial value $\geq 1000 \text{ Mfi or } 50 \text{ fi}\cdot\text{F}$, (Whichever is smaller) Within the specified initial value	Per AEC-Q200-002 Pre-treatment	Perform heat treatment at (150 +0/−10) °C for 1 h, then soak at room temperature for (24 ± 2) h, then measure.

Table 1: Specifications and Test Methods

No.	Item AEC-Q200 Test Item	Specification Class 2 (High dielectric constant type)	Test Method	
13	Solderability	Appearance 95% of the terminations is to be soldered evenly and continuously	Pre-heating Temp.: 155 °C/Time: 4 h Test Method Solder bath Flux Solution of rosin ethanol Solder alloy Sn-Ag-Cu (Lead Free Solder) Temperature (245 ± 5) °C Duration of immersion (5.0 ± 0.5) s Depth of immersion (10 ± 1) mm	
14	Electrical Characterization	Capacitance	Within the specified tolerance	Measurement Temperature 18 °C-28 °C
15		DF	0.125 max	Relative Humidity ≤ 80% RH Measurement Frequency $C \leq 10 \mu\text{F}$, $f = 1.0 \pm 0.1 \text{ KHz}$; $C > 10 \mu\text{F}$, $f = 120 \pm 24 \text{ Hz}$ Measurement Voltage $C \leq 10 \mu\text{F}$, $U = 1.0 \pm 0.2 \text{ Vrms}$; $C > 10 \mu\text{F}$, $U = 0.5 \pm 0.1 \text{ Vrms}$
16		IR (Room Temp.)	≥ 1000 Mfi or 50 fi•F, (Whichever is smaller)	Measurement Temperature 25 °C Measurement Voltage $U_R < 500 \text{ V}$: U_R $U_R \geq 500 \text{ V}$: $500 \text{ V} \pm 50 \text{ V}$ Charging Time 1 min The charge/discharge current ≤ 50 mA
17		IR (High Temp.)	≥ 100 Mfi or 5 fi•F, (Whichever is smaller)	Measurement Temperature 85 °C Measurement Voltage $U_R < 500 \text{ V}$: U_R $U_R \geq 500 \text{ V}$: $500 \text{ V} \pm 50 \text{ V}$ Charging Time 1 min The charge/discharge current ≤ 50 mA
18		Voltage proof	No defects or abnormalities.	Test Voltage ≥ 2.5 × U_R Applied Time $t = 1-5 \text{ s}$ The charge/discharge current ≤ 50 mA
19	Board Flex	Appearance Cap. Change IR (Room Temp.) DF	No defects or abnormalities. $\Delta C/C \leq \pm 10\%$ ≥ 1000 Mfi or 50 fi•F, (Whichever is smaller) Within the specified initial value	Mounting method Solder the capacitor to the test substrate as shown in Fig 2 Pressurization Method Shown in Fig 3 Speed 1 mm/s Flexure 2 mm Holding Time $t = (60 \pm 1) \text{ s}$ then measure the capacitance

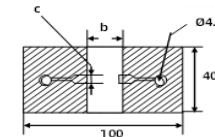


Fig. 2

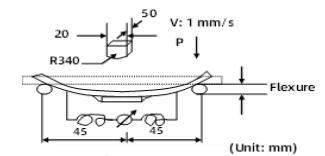
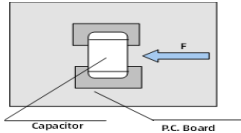
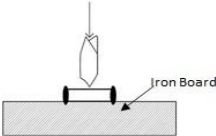
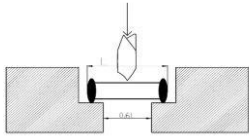


Fig. 3

Table 1: Specifications and Test Methods

No.	Item AEC-Q200 Test Item		Specification Class 2 (High dielectric constant type)	Test Method	
20	Terminal Strength	Appearance	No defects or abnormalities.	Subjected to 3 cycles of lead-free reflow at 260 °C (standard profile) for thermal shock testing, with ~30 minutes between cycles.	
		Cap. Change	Within the specified initial value	Mounting method	Solder the capacitor to the test substrate as shown in Fig 4
		IR (Room Temp.)	$\geq 1000 \text{ M}\Omega$ or $50 \text{ }\mu\text{F}$, (Whichever is smaller)	Holding Time	$t = (60 \pm 1) \text{ s}$
		DF	Within the specified initial value	Pushing force	0402: $F = 2 \text{ N}$
				 Fig. 4	
21	Beam Load Test	Destruction value	Should be exceed following one	Mounting method	Place the capacitor in the beam load fixture as Fig 5/6
			Size Code Destruction value 0402 $\geq 8 \text{ N}$	Speed supplied the Stress Load	0402 min: 0.5 mm/s, 0201: 0.1 mm/s
				<Size Code: 0805 max >	<Size Code: 1206 min>
				 Fig. 5	 Fig. 6
22	Temperature Characteristics of Capacitance		X5R: $\Delta C/C \leq \pm 15\%$	Pre-treatment	Perform heat treatment at $(150 \pm 10)^\circ\text{C}$ for 1 h, then soak at room temperature for $(24 \pm 2) \text{ h}$, then measure.
				Measure the capacitance separately in 25 °C, θ_1 , 25 °C, θ_2 , 25 °C, should satisfied related Temperature Coefficient of Capacitance .	
				X5R	$\theta_1 = -55^\circ\text{C}$, $\theta_2 = 85^\circ\text{C}$
				T.C. Measurement Voltage	$\leq 1.0 \pm 0.2 \text{ Vrms}$ ※ [※ Please contact our technical support staff for more information.]

4. Packaging, Shipment and storage

4.1 Packaging

4.1.1 packaging type

Reel Packaging (standard carrier tape disc packaging), single disc smallest package see ⑧ Packaging Code

First packaging: Each multi-disc material is packed into a box.

The second packaging: the first packaged packaging box is loaded into the paper packaging box, and the remaining space in the box is filled with light auxiliary materials.

The above packaging forms can also be packaged according to user needs.

4.1.2 Carrier Tape size

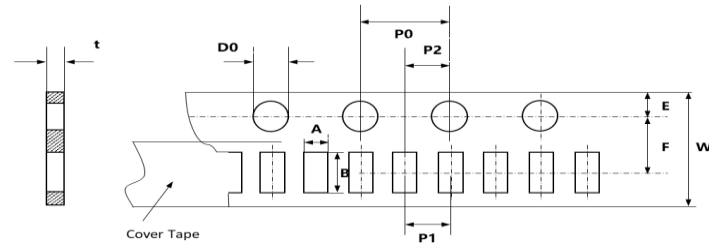


Fig. 7-1 0402 (Paper tape/ 2 mm pitch)

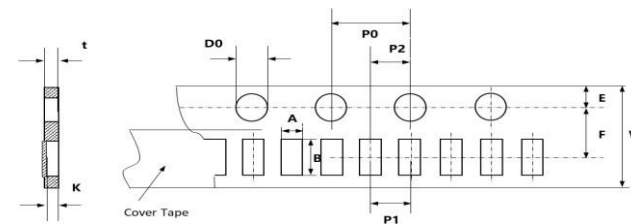


Fig. 7-2 0201 (Paper tape/ 2 mm pitch)

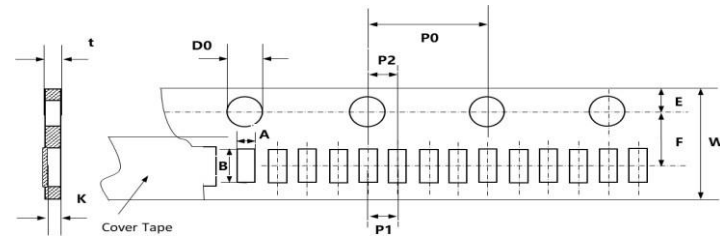


Fig. 7-3 0201 (Paper tape/ 1 mm pitch)

Table 2-1: Carrier size (Size Code: 0201,0402)

(Unit:mm)

Size Code	Thickness code	Carrier Tape Type	Packaging Code	A	B	F	P1	E	D0	P2	K	W	P0	t
0201	A	Paper	T	0.38 ± 0.03	0.68 ± 0.03	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	0.36 ± 0.02	8.00 ± 0.10	4.00 ± 0.10	0.5 max
0201	A	Paper	J	0.38 ± 0.03	0.68 ± 0.03	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	0.36 ± 0.02	8.00 ± 0.10	4.00 ± 0.10	0.5 max
0201	A	Paper	D	0.38 ± 0.03	0.68 ± 0.03	3.50 ± 0.05	1.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	1.00 ± 0.05	0.36 ± 0.02	8.00 ± 0.10	4.00 ± 0.10	0.5 max
0201	A	Paper	L	0.38 ± 0.03	0.68 ± 0.03	3.50 ± 0.05	1.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	1.00 ± 0.05	0.36 ± 0.02	8.00 ± 0.10	4.00 ± 0.10	0.5 max
0201	J	Paper	T	0.40 ± 0.04	0.70 ± 0.04	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	0.38 ± 0.04	8.00 ± 0.10	4.00 ± 0.10	0.5 max
0201	J	Paper	J	0.40 ± 0.04	0.70 ± 0.04	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	0.38 ± 0.04	8.00 ± 0.10	4.00 ± 0.10	0.5 max
0201	J	Paper	D	0.40 ± 0.04	0.70 ± 0.04	3.50 ± 0.05	1.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	1.00 ± 0.05	0.38 ± 0.04	8.00 ± 0.10	4.00 ± 0.10	0.5 max
0201	J	Paper	L	0.40 ± 0.04	0.70 ± 0.04	3.50 ± 0.05	1.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	1.00 ± 0.05	0.38 ± 0.04	8.00 ± 0.10	4.00 ± 0.10	0.5 max
0201	X	Paper	T	0.44 ± 0.06	0.74 ± 0.06	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	0.40 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	0.6 max
0201	X	Paper	J	0.44 ± 0.06	0.74 ± 0.06	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	0.40 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	0.6 max
0201	F	Paper	T	0.44 ± 0.06	0.74 ± 0.06	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	0.40 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	0.6 max
0402	B	Paper	T	0.63 ± 0.05	1.13 ± 0.05	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.10	4.00 ± 0.10	0.8 max
0402	B	Paper	J	0.63 ± 0.05	1.13 ± 0.05	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.10	4.00 ± 0.10	0.8 max
0402	N	Paper	T	0.70 ± 0.10	1.20 ± 0.10	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.10	4.00 ± 0.10	0.8 max
0402	N	Paper	J	0.70 ± 0.10	1.20 ± 0.10	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.10	4.00 ± 0.10	0.8 max
0402	C	Paper	T	0.75 ± 0.10	1.30 ± 0.10	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.10	4.00 ± 0.10	0.8 max
0402	C	Paper	J	0.75 ± 0.10	1.30 ± 0.10	3.50 ± 0.05	2.00 ± 0.05	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.10	4.00 ± 0.10	0.8 max

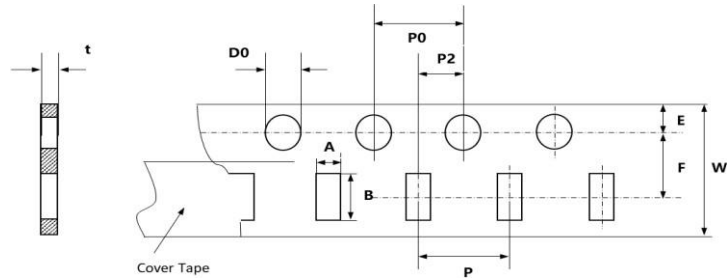


Fig. 7-4 0603, 0805, 1206, 1210 (Paper tape)

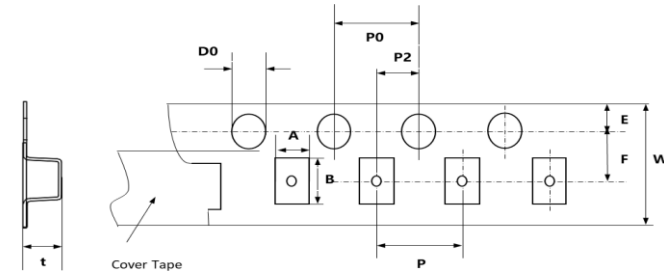


Fig. 7-5 0603, 0805, 1206, 1210 (Plastic tape)

Table 2-2: Carrier size (Size Code:0603, 0805, 1206, 1210)

(Unit:mm)

Size Code	Thickness code	Carrier Tape Type	Packaging Code	A	B	F	P	E	D0	P2	K	W	P0	t
0603	D	Paper	T	1.00 ± 0.10	1.80 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0603	D	Paper	A	1.00 ± 0.10	1.80 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0603	D	Plastic	O	1.00 ± 0.10	1.80 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0603	D	Paper	W	1.00 ± 0.10	1.80 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0603	K	Paper	T	1.10 ± 0.10	1.90 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0603	K	Paper	A	1.10 ± 0.10	1.90 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0603	K	Plastic	O	1.10 ± 0.10	1.90 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0603	K	Paper	W	1.10 ± 0.10	1.90 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0603	K	Plastic	Q	1.10 ± 0.10	1.90 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0603	K	Plastic	R	1.10 ± 0.10	1.90 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0805	C	Paper	T	1.45 ± 0.10	2.20 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	0.9 max
0805	C	Plastic	R	1.45 ± 0.10	2.20 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	0.9 max
0805	K	Paper	T	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0805	K	Plastic	R	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0805	K	Plastic	E	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0805	Y	Paper	T	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0805	Y	Plastic	E	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0805	Y	Plastic	P	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0805	Y	Plastic	R	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
0805	G	Plastic	R	1.45 ± 0.10	2.20 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.75 max
0805	G	Plastic	P	1.45 ± 0.10	2.20 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.75 max
0805	G	Plastic	O	1.45 ± 0.10	2.20 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.75 max
0805	H	Plastic	R	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.00 max
0805	H	Plastic	P	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.00 max
0805	H	Plastic	O	1.45 ± 0.20	2.20 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.00 max
1206	E	Plastic	R	1.80 ± 0.20	3.40 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
1206	E	Plastic	P	1.80 ± 0.20	3.40 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.15 max
1206	O	Plastic	R	1.80 ± 0.20	3.40 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.45 max
1206	O	Plastic	P	1.80 ± 0.20	3.40 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	1.45 max

Table 2-2: Carrier size (Size Code:0603, 0805, 1206, 1210)

(Unit:mm)

Size Code	Thickness code	Carrier Tape Type	Packaging Code	A	B	F	P	E	D0	P2	K	W	P0	t
1206	L	Plastic	P	1.80 ± 0.20	3.40 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.50 max
1206	L	Plastic	R	1.80 ± 0.20	3.40 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.50 max
1206	L	Plastic	E	1.80 ± 0.20	3.40 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.50 max
1206	P	Plastic	P	1.90 ± 0.20	3.50 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.50 max
1210	Q	Plastic	F	2.70 ± 0.20	3.50 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.50 max
1210	Q	Plastic	S	2.70 ± 0.20	3.50 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.50 max
1210	Q	Plastic	Z	2.70 ± 0.20	3.50 ± 0.20	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	2.50 max
1210	R	Plastic	Z	2.70 ± 0.20	3.50 ± 0.30	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	3.00 max
1210	R	Plastic	S	2.70 ± 0.20	3.50 ± 0.30	3.50 ± 0.05	4.00 ± 0.10	1.75 ± 0.10	1.55 ± 0.05	2.00 ± 0.05	/	8.00 ± 0.20	4.00 ± 0.10	3.00 max

4.1.3 Disc size

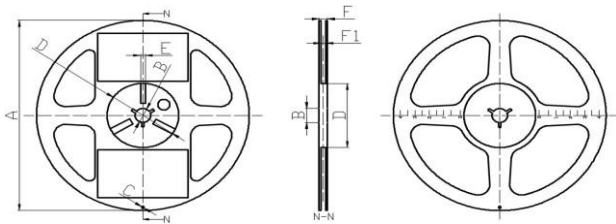


Fig. 8 Disc (Width of carrier-8 mm)

Table 3: Disc size

(Unit:mm)

Disc size	Width of carrier	A	B	C	D	E	F	F1	Size Code
7"	8.00 ± 0.10	Φ178 ± 2.0	Φ13 ± 1.0	Φ4.0 ± 0.5	Φ60 ± 2.0	4.0 ± 1.0	11.5 ± 1.0	10.0 ± 2.0	All
13"	8.00 ± 0.10	Φ330 ± 2.0	Φ13 ± 1.0	Φ4.0 ± 0.5	Φ108 ± 2.0	4.0 ± 1.0	13.5 ± 2.0	10.0 ± 2.0	All

4.1.4 Carrier Tape specifications

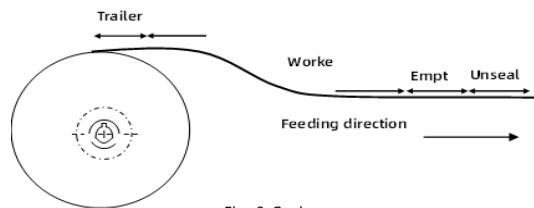


Fig. 9 Carrier

Packaging	The minimum length of the reserved spaces		
Carrier	Trailer	Empty	Unseal
	60 mm	200 mm	160 mm

4.1.5 Performance of Carrier Taping

4.1.5.1 Strength of Carrier Tape and Top Cover Tape

a. Carrier Tape

When a tensile force 1.02 kgf is applied in the direction to unreel the tape, the tape shall withstand this force.

b. Top cover Tape

When a tensile force 1.02 kgf is applied to the tape, the tape shall withstand this force.

4.1.5.2 Peeling Strength of Top Cover Tape

Unless otherwise specified, the peeling strength of top cover tape shall be within 10.2 gf to 71.4 gf when the top cover tape is pulled at a speed of 300 mm/min with the angle of 0° to 15° (see Fig. 10).

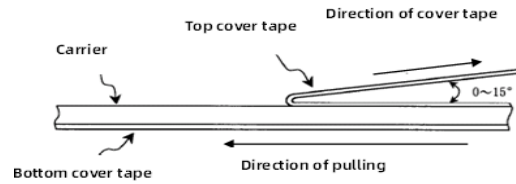


Fig. 10 Cover tape peel-off force

2. Shipment

Transport packaging products to adapt to the modern means of transport, but the product in the process of transport to prevent rain and acid and alkali corrosion, shall not be whipped extrusion casting and gravity.

3. Storage

1. Storage conditions:

The recommended temperature is less than 30 °C.

A temperature is 5 °C to 40 °C and a relative humidity is 20% to 70% as a standard condition.(MSL Level 1)

MLCC may be affected by the storage conditions. Please use them promptly after delivery.

High temperature and humidity conditions and/or prolonged storage may cause deterioration of the packaging materials.

If more than one year has elapsed since delivery, also check the solderability before use.

2. Corrosive gas can react with the termination (external) electrodes or lead wires of capacitors, and result in poor solderability.

Do not store the capacitors in an atmosphere consisting of corrosive gas (e.g.,hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)

5. MLCC Application of Technical Requirements

5.1 Circuit Design

5.1.1 Operating Temperature

- Do not use capacitor above the maximum allowable operating temperature.
- Surface temperature including self-heating should be below maximum operating temperature.

5.1.2 Operating Voltage

The operating voltage for capacitors must always be lower than their rated voltage.

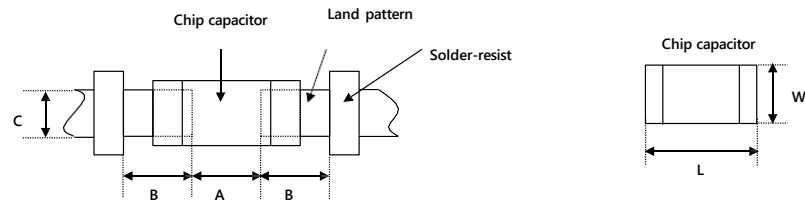
5.2 PCB Design

5.2.1 Design of Land-patterns

When the capacitors are mounted on a PCB, the amount of solder at the terminations has a direct effect on the performance of the capacitors.

The greater the amount of solder, the higher the stress on the capacitor. Therefore, when designing land-patterns, it is necessary to consider the appropriate size and configuration of the solder pads.

Size and recommended land dimensions are shown in the following figure and table.



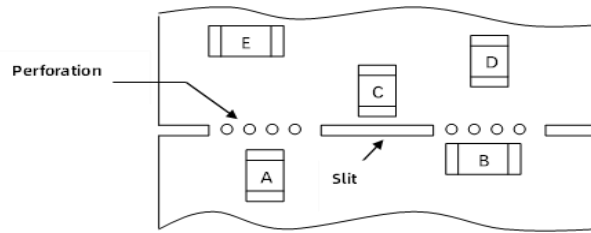
Recommended land dimensions for reflow-soldering

(unit: mm)

Size Code	Length	Width	Tolerance	A	B	C
0201	0.6	0.3	± 0.03	0.20 - 0.25	0.20 - 0.30	0.20 - 0.35
0201	0.6	0.3	± 0.05	0.20 - 0.25	0.25 - 0.35	0.30 - 0.40
0201	0.6	0.3	± 0.09, ± 0.1	0.23 - 0.30	0.25 - 0.35	0.30 - 0.40
0402	1.0	0.5	± 0.05	0.30 - 0.50	0.35 - 0.45	0.40 - 0.60
0402	1.0	0.5	± 0.15, ± 0.20	0.40 - 0.60	0.40 - 0.50	0.50 - 0.70
0402	1.0	0.5	± 0.30	0.40 - 0.60	0.40 - 0.50	0.50 - 0.80
0603	1.6	0.8	± 0.10	0.60 - 0.80	0.60 - 0.70	0.60 - 0.80
0603	1.6	0.8	± 0.20	0.70 - 0.90	0.70 - 0.80	0.80 - 1.00
0603	1.6	0.8	± 0.25, ± 0.30	0.70 - 0.90	0.70 - 0.90	0.80 - 1.10
0805	2.0	1.25	± 0.10, ± 0.15, ± 0.20	1.00 - 1.40	0.60 - 0.80	1.20 - 1.40
0805	2.0	1.25	± 0.25	1.00 - 1.40	0.70 - 0.90	1.35 - 1.55
1206	3.2	1.6	± 0.15, ± 0.20	1.80 - 2.00	0.90 - 1.20	1.50 - 1.70
1206	3.2	1.6	± 0.30	1.90 - 2.10	1.00 - 1.30	1.60 - 1.90
1210	3.2	2.5	± 0.20	2.00 - 2.40	1.00 - 1.20	2.50 - 2.70
1210	3.2	2.5	± 0.30	2.00 - 2.40	1.10 - 1.30	2.50 - 2.80

5.2.2 Capacitor Layout on PC Board

Mechanical stress varies according to the location of capacitors on PC board. The recommendation for better design is as follows

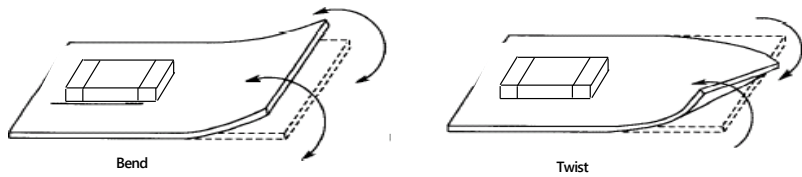


The stress in capacitors is in the following order: $A > B = C > D > E$

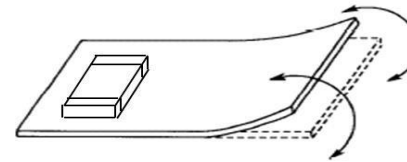
Pay attention not to bend or distort the PC board otherwise the capacitor may crack.

Please refer to the following examples of good and bad capacitors layout.

a. Not recommended



b. Recommended



5.2.3 Solder Buildup and Soldering

a. Examples of soldering method not recommended



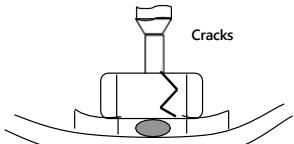
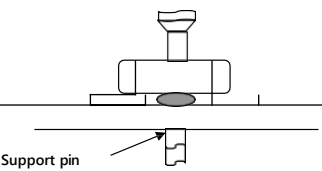
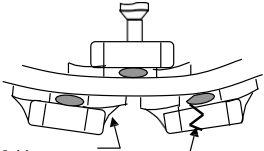
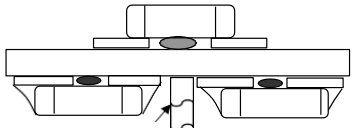
b. Examples of soldering method recommended



5.3 Consideration for Automatic Placement

- If the mounting head is adjusted too low, it may induce excessive stress in the chip capacitor to result in cracking. Please take following precautions
- a. Adjust the bottom dead center of the mounting head to reach on the PC board surface and not press it ;
 - b. Adjust the mounting head pressure to be 1N to 3N of static weight ;
 - c. To minimize the impact energy from mounting head, it is important to provide support from the bottom side of the PC board.

Please refer to the following samples

Mounting	Not recommended	Recommended
Singel-sided Mounting	 Cracks	 Support pin
Double-sided Mounting	 Solder peeling Cracks	 Support pin

4. Soldering

1. Flux Selection

- a. It is recommended to use a mildly activated rosin flux (less than 0.1wt% chlorine). Strong flux is not recommended.
- b. Please provide proper amount of flux. Excessive flux must be avoided.
- c. When water-soluble flux is used, enough washing is necessary.

5.4.2 Recommended Soldering Profile

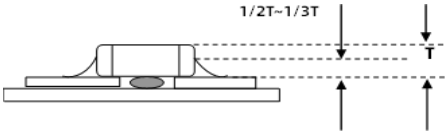


5.4.2.1 Reflow Soldering Condition

NO.	Reflow Soldering zone	Reflow Soldering Condition
①	Preheating 1	$\leq 3\text{ }^{\circ}\text{C/s}, \geq 60\text{ s}$
②	Constant temperature	$150^{\circ}\text{C}-200^{\circ}\text{C}, 60\text{ s}-120\text{ s}, \leq 1\text{ }^{\circ}\text{C/s}$
③	Preheating 1	$1-5\text{ }^{\circ}\text{C/s}$
④	Soldering 1	Above $217\text{ }^{\circ}\text{C}$, $60-150\text{ s}$
⑤	Soldering 1	Above $260\text{ }^{\circ}\text{C}$, over 10 s
⑥	Natural cooling	$\leq 6\text{ }^{\circ}\text{C/s}$

Caution

a.Excessive solder will induce higher tensile force in chip capacitor when temperature changes and result in cracking. Insufficient solder may detach the capacitor from the PC board.
The ideal condition is to have solder mass controlled to 1/2 to 1/3 of the thickness of the capacitors.



b.Soldering duration should be kept as close to recommended times as possible, because excessive duration can detrimentally affect solderability.
c.The peak temperature of reflow soldering is $245\text{ }^{\circ}\text{C} \pm 15\text{ }^{\circ}\text{C}$.

6. All products in this specification comply with the EU RoHS directive

The EU RoHS Directive refers to the "Directive 2011/65/EU on the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment" stipulated by the European Union.

ORIGINAL MFG PART No.: **A0402X5R105K250NTB**

PRODUCT NAME:	MLCC For Automotive A Series SMD 0402 X5R 1 μ F $\pm$ 10% 25V
REVISION:	A3
NEXTGEN ORDER PART CODE*:	A0402W105K250B
CROSS REF. PART NO.:	
ORIGINAL MFG PART NO.:	A0402X5R105K250NTB
ORIGINAL MANUFACTURER:	EYang Technology/Eyang MLCC

*Image shown is a representation only.
Exact specifications should be obtained
from the product dimension*

*: Please Indicate this Part Code For RFQ/Order Support

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CODE	NAME	KEY SPECIFICATION OPTION
A	Series Code	A: Multilayer Ceramic Chip Capacitors For Automotive
0402	Case Size	0105 : L0.40*W0.20mm; 0201 : L0.60*W0.30mm; 0402 : L1.00*W0.50mm; 0603 : L1.60*W0.80mm 0805 : L2.00*W1.25mm; 1206 : L3.20*W1.60mm; 1210 : L3.20*W2.50mm
W	Temperature Characteristics	N: NP0 (COG); B: X7R; W: X5R; S: X6S; Y: Y5V; T: X7S; R: X7T
105	Capacitance	Two significant digits followed by number of Zero, The 3rd digit signifies the multiplying factor, and letter R is decimal point. 0R3: 0.3pF; 820: 82pF; 102: 1000pF; 680: 68pF; 471: 470pF; 105: 1μF
K	Capacitance Tolerance	A: ±0.05pF; B: ±0.1pF; C: ±0.25pF; D: ±0.5pF; F: ±1%; G: ±2%; J: ±5%; K: ±10% L: ±15%; M: ±20%; N: ±30%; P: ±0.02pF; X: ±40%; S: 50%/-20%; Y: 150%/-20% Z: 80%/-20%
250	Rated Voltage	Two significant digits followed by No. of zeros. "R" is in place of decimal point. 6R3: 6.3 VDC; 160: 16 VDC; 250: 25 VDC; 100: 10 VDC; 500: 50 VDC; 101: 100 VDC
B	Case Thickness	B: 0.8mm Max, See Page 6 (T's Symbol) for Different part code
XX	Internal Control Code	Blank: N/A; XX: Letter A~Z, a~z or digits (0~9) for Special/Custom Parameters

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